



**P-Ch 150V Fast Switching MOSFETs**

**Applications**

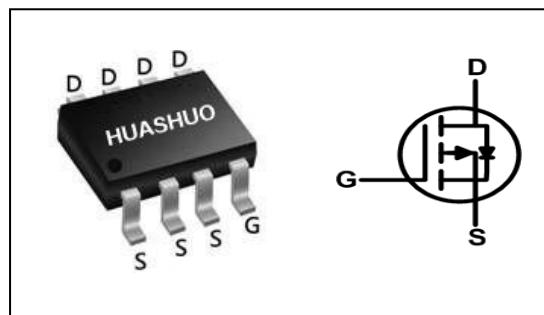
- Load Switch.
- Power Management.
- LED Backlighting.
- Networking application.

**Product Summary**

$V_{DS}$	-150	V
$R_{DS(ON),max}$	780	mΩ
$I_D$	-1.3	A

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

**SOP8 Pin Configuration**



**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	-1.3	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	-0.89	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-4.4	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	12.5	mJ
$I_{AS}$	Avalanche Current	-5	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	40	°C/W



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**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-150	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-1\text{A}$	---	650	780	$\text{m}\Omega$
		$V_{\text{GS}}=-6\text{V}$ , $I_{\text{D}}=-0.5\text{A}$	---	700	980	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-2.0	-3.0	-4.0	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	5.42	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSs}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-120\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=-120\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=150^\circ\text{C}$	---	---	30	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	12	---	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-75\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-1\text{A}$	---	10.5	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	3.2	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	2.3	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-30\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_g=6\Omega$ , $I_{\text{D}}=-1\text{A}$	---	21	---	$\text{ns}$
$T_r$	Rise Time		---	17	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	40	---	
$T_f$	Fall Time		---	18	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-75\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	715	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	21	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	14	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,6</sup>	$V_{\text{G}}=V_{\text{D}}=0\text{V}$ , Force Current	---	---	-1	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=-50\text{V}$ ,  $V_{\text{GS}}=-10\text{V}$ ,  $L=1\text{mH}$ ,  $I_{\text{AS}}=-5\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



P-Channel Typical Characteristics

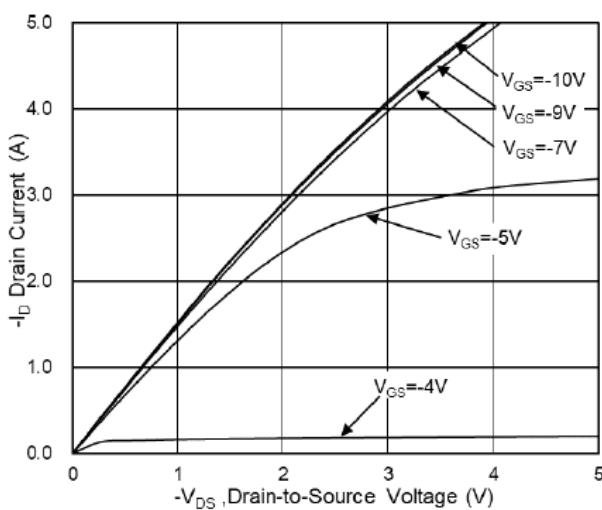


Fig.1 Typical Output Characteristics

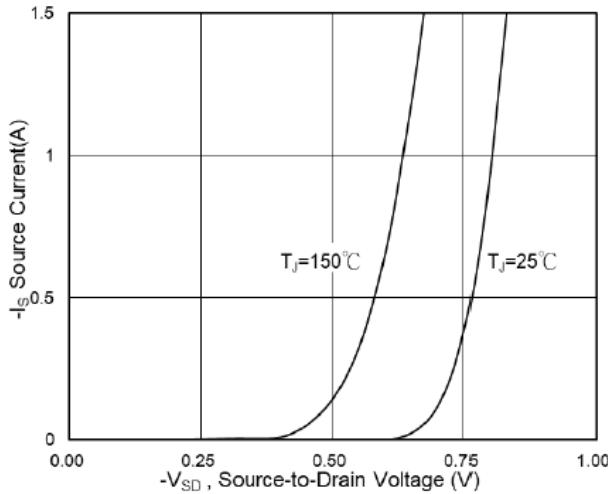


Fig.3 Forward Characteristics Of Reverse

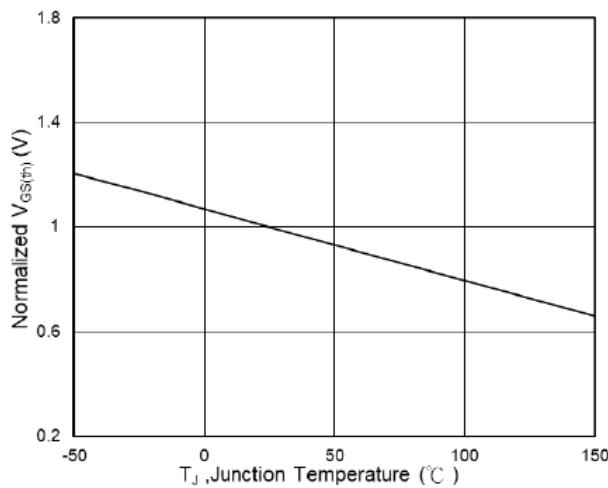


Fig.5 Normalized  $V_{GS(\text{th})}$  vs.  $T_J$

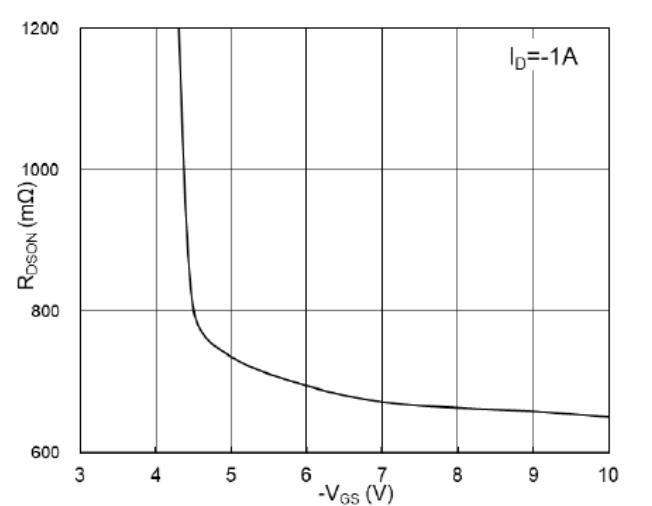


Fig.2 On-Resistance vs. G-S Voltage

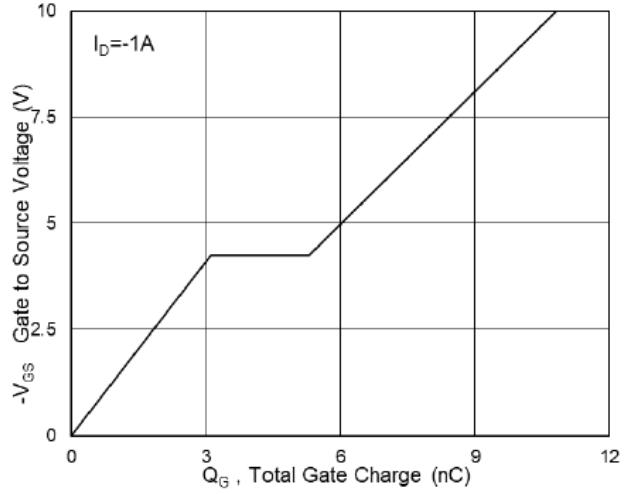


Fig.4 Gate-Charge Characteristics

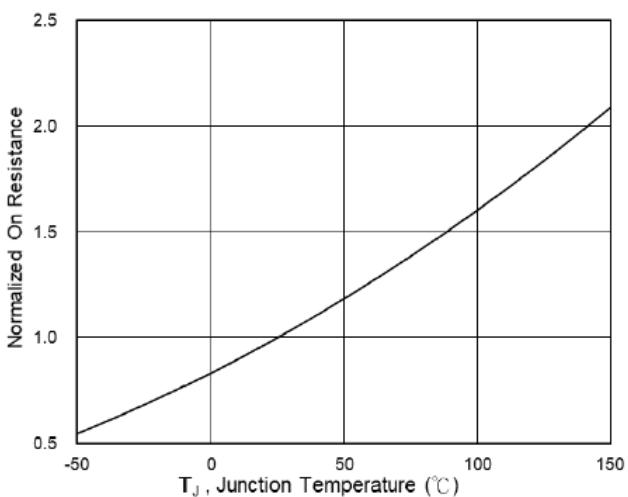


Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$



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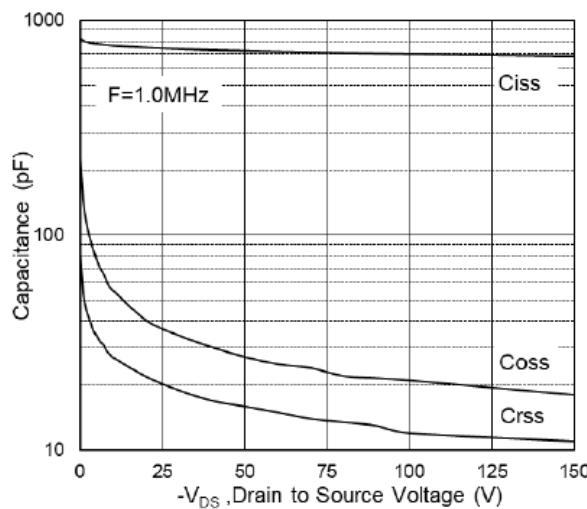


Fig.7 Capacitance

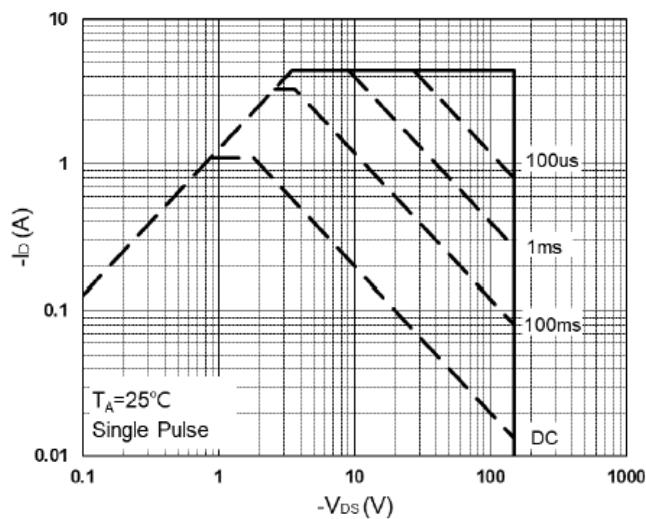


Fig.8 Safe Operating Area

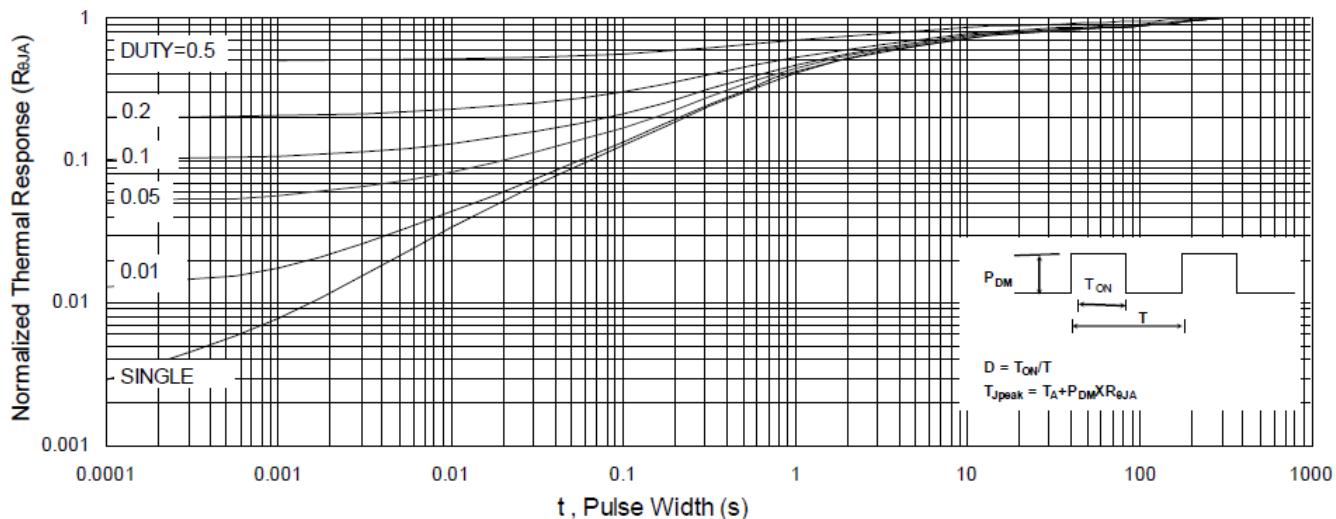


Fig.9 Normalized Maximum Transient Thermal Impedance

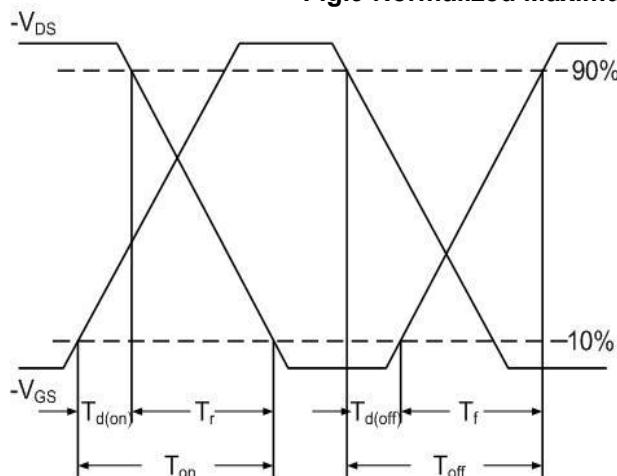


Fig.10 Switching Time Waveform

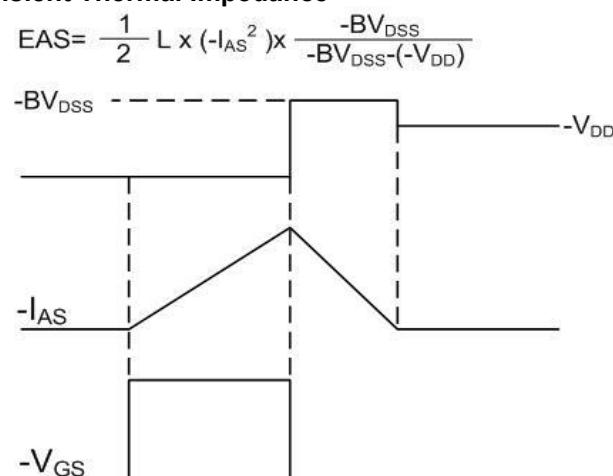


Fig.11 Unclamped Inductive Waveform



## Ordering Information

Part Number	Package code	Packaging
HSM01P15	SOP-8	2500/Tape&Reel

